



30V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C		
30V	6mΩ @ V _{GS} = 10V	60A		
307	9mΩ @ V _{GS} = 4.5V	48A		

Description

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- **Power Management Functions**
- Analog Switch

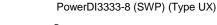
Features

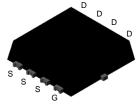
- Low RDS(ON) Ensures On-State Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher **Density End Products**
- Occupies just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free, "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

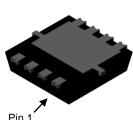
Mechanical Data

- Case: PowerDI®3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (63)
- Weight: 0.03 grams (Approximate)

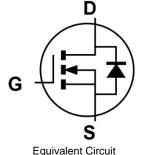




Top View







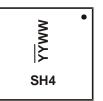
Ordering Information (Note 4)

Part Number	Case	Packaging	
DMT35M4LFVW-7	PowerDI3333-8 (SWP) (Type UX)	2,000/Tape & Reel	
DMT35M4LFVW-13	PowerDI3333-8 (SWP) (Type UX)	3,000/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



SH4 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 20 = 2020) WW = Week Code (01 to 53)



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	30	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Prain Current V 40V (Note 6)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	lo	16 13	А
Continuous Drain Current, V _{GS} = 10V (Note 6)	Steady State	$T_C = +25$ °C $T_C = +70$ °C	lo	60 48	А
Maximum Body Diode Forward Current (Note 6)	Is	2.3	Α		
Pulsed Drain Current (380µs Pulse, Duty Cycle = 19	I _{DM}	110	Α		
Pulsed Drain Body Diode Forward Current (380µs F	I _{SM}	110	Α		
Avalanche Current (L = 0.1mH) (Note 8)			las	22	Α
Avalanche Energy (L = 0.1mH) (Note 8)	Eas	25	mJ		

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	PD	1.5	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	83.3	°C/W
Total Power Dissipation (Note 6)	PD	2.2	W	
Thermal Resistance, Junction to Ambient (Note 6) Steady State		RθJA	55	°C/W
Thermal Resistance, Junction to Case (Note 7)	R ₀ JC	3.9	C/VV	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

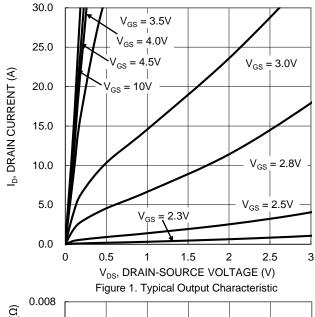
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

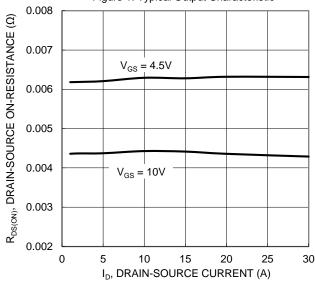
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)					l .		
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μA	$V_{DS} = 24V$, $V_{GS} = 0V$	
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	Vgs(TH)	1.15	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D		4.6	6	mΩ	V _G S = 10V, I _D = 20A	
Static Diani-Source On-Resistance	R _{DS(ON)}	_	6.5	9		$V_{GS} = 4.5V, I_D = 15A$	
Diode Forward Voltage	VsD	_	0.7	1	V	V _G S = 0V, I _S = 1A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	982	_		$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Output Capacitance	Coss	_	903	_	pF		
Reverse Transfer Capacitance	Crss	_	27	_			
Gate Resistance	Rg	_	2.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	7.9	_		V _{DD} = 15V, I _D = 9A	
Total Gate Charge (V _{GS} = 10V)	Qg	_	16.1	_	nC		
Gate-Source Charge	Q _{gs}	_	3.6	_	IIC		
Gate-Drain Charge	Qgd	_	1.2	_			
Turn-On Delay Time	t _{D(ON)}	_	8.1	_			
Turn-On Rise Time	t _R	_	2.2	_		$V_{DD} = 15V, V_{GS} = 10V,$	
Turn-Off Delay Time	tD(OFF)	_	16.8	_	ns	$R_g = 3\Omega$, $I_D = 9A$	
Turn-Off Fall Time	tF	_	5.7	_			

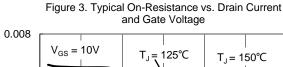
5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided. Notes:

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 9. Short duration pulse test used to minimize self-heating effect.
 10. Guaranteed by design. Not subject to product testing.









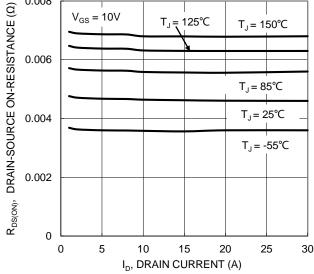
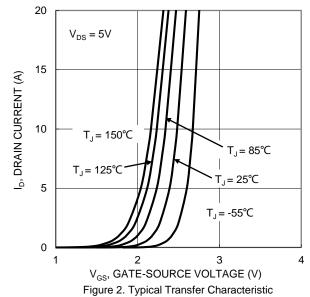


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



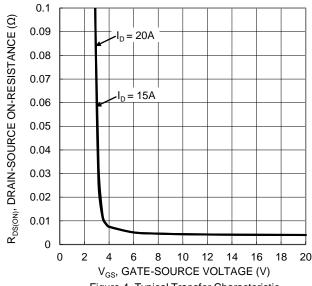


Figure 4. Typical Transfer Characteristic

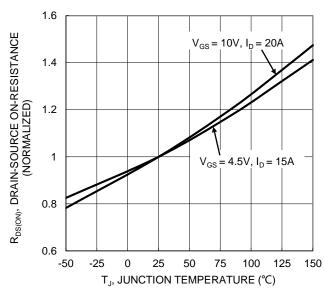


Figure 6. On-Resistance Variation with Junction Temperature





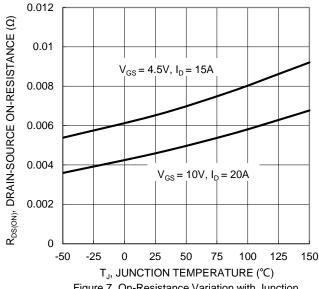
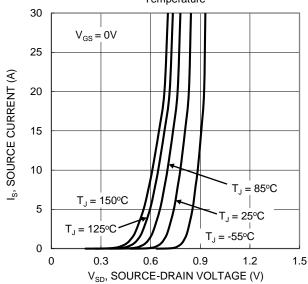
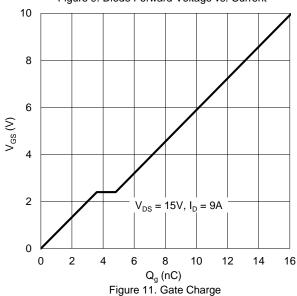


Figure 7. On-Resistance Variation with Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current



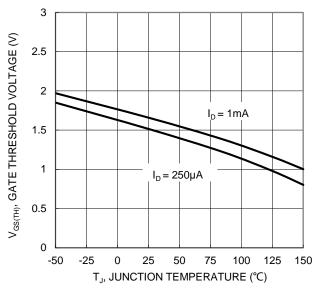
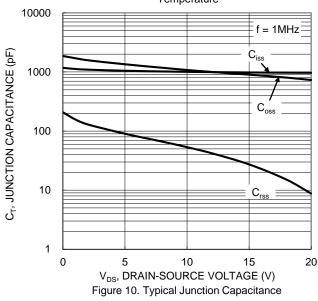


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R_{DS(ON)} Limited 100 ID, DRAIN CURRENT (A) 10 $P_{w} = 100 \mu s$ $P_{W} = 100 ms$ $T_{J(Max)} = 150^{\circ}C$ $T_C = 25^{\circ}C$ Single Pulse DUT on Infinite Heatsink $V_{GS} = 10V$ 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V)



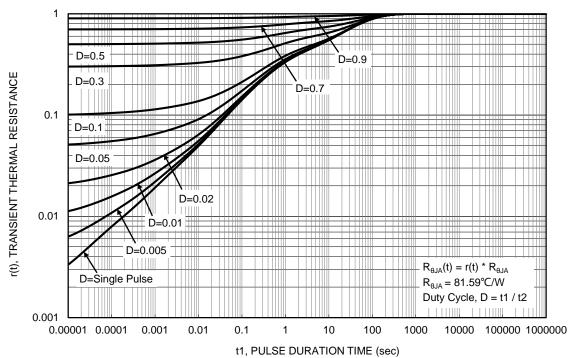


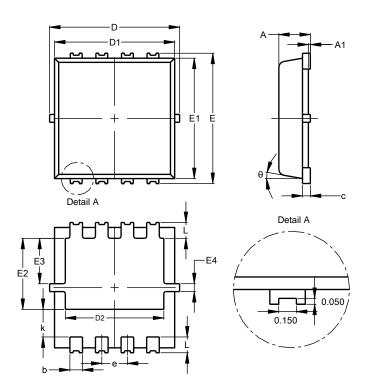
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)

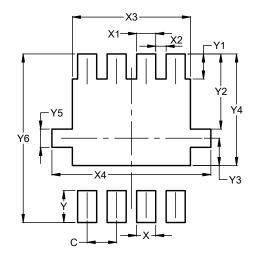


PowerDI3333-8 (SWP)					
(Type UX)					
Dim	Min	Min Max T			
Α	0.75	0.85	0.80		
A1	0.00	0.05			
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	E2 1.60 2.00 1.8		1.80		
E3	0.95	1.35	1.15		
E4	0.10	0.30	0.20		
е	_	_	0.65		
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)				
С	0.650				
Х	0.420				
X1	0.420				
X2	0.230				
Х3	2.600				
X4	3.500				
Υ	0.700				
Y1	0.550				
Y2	1.650				
Y3	0.600				
Y4	2.450				
Y5	0.400				
Y6	3.700				



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